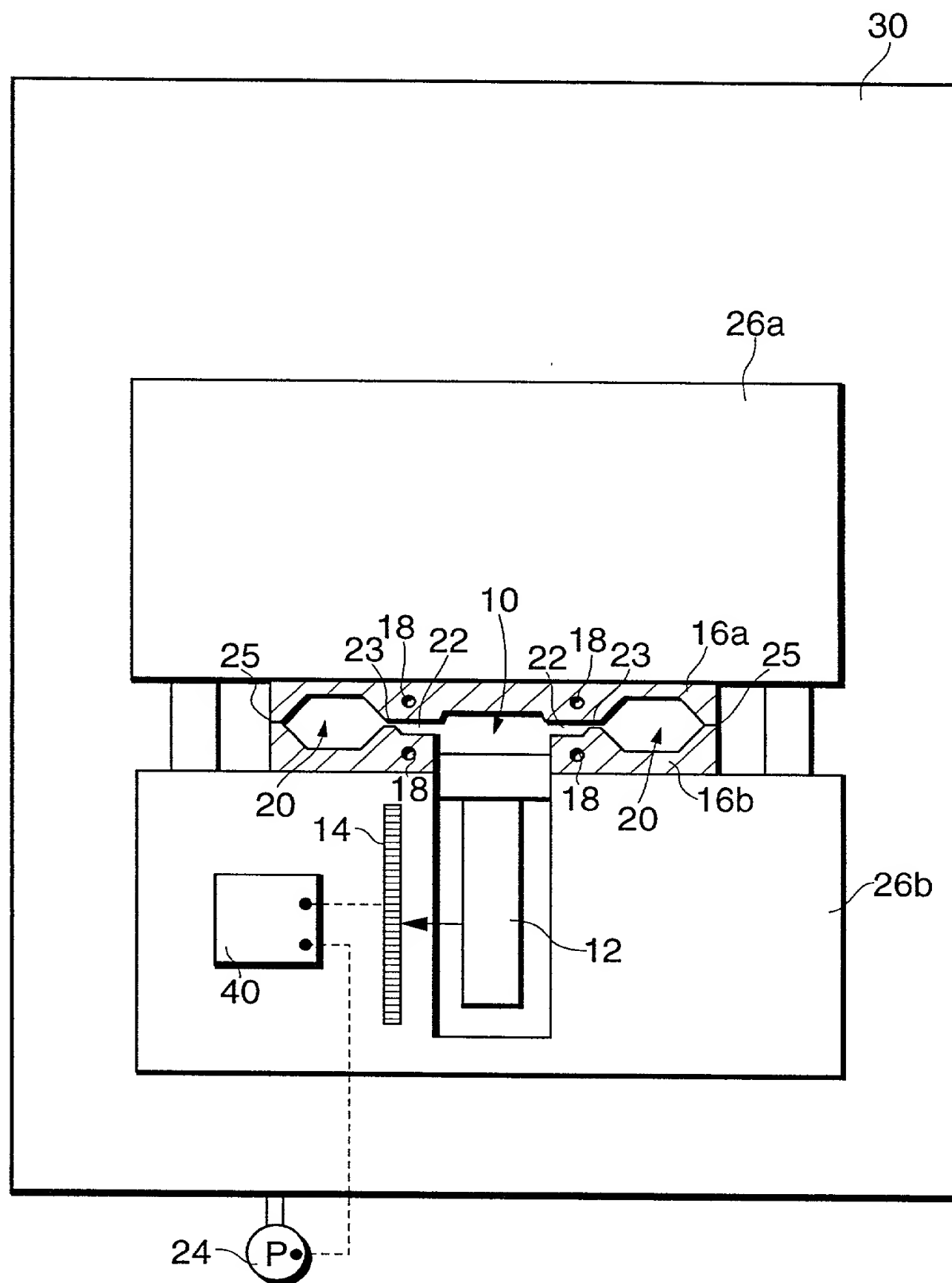
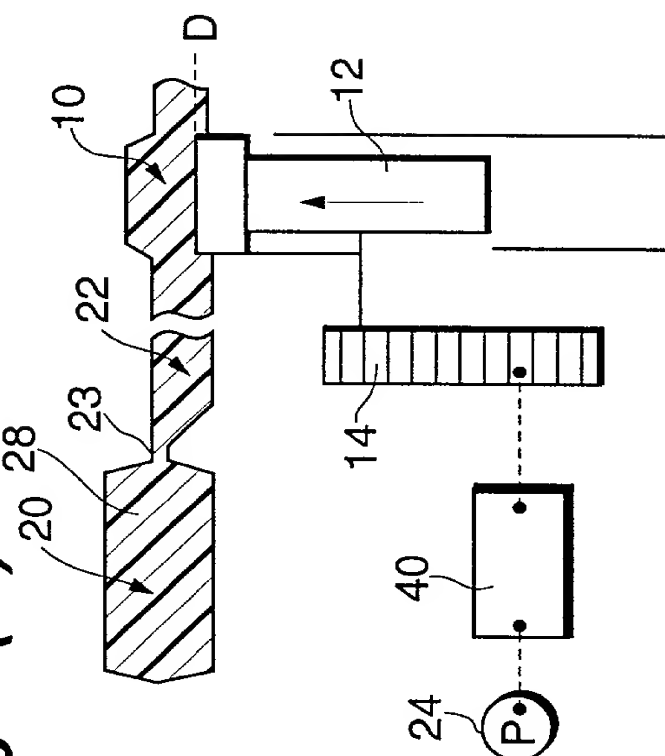
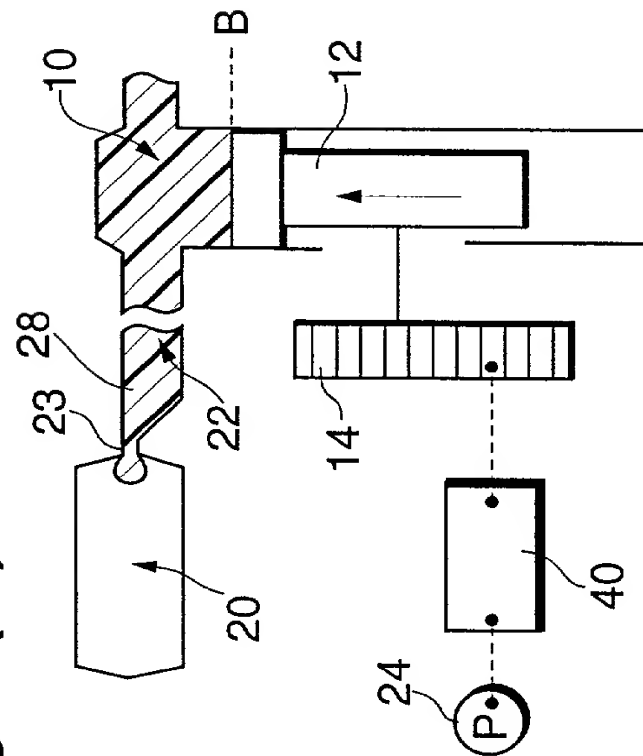


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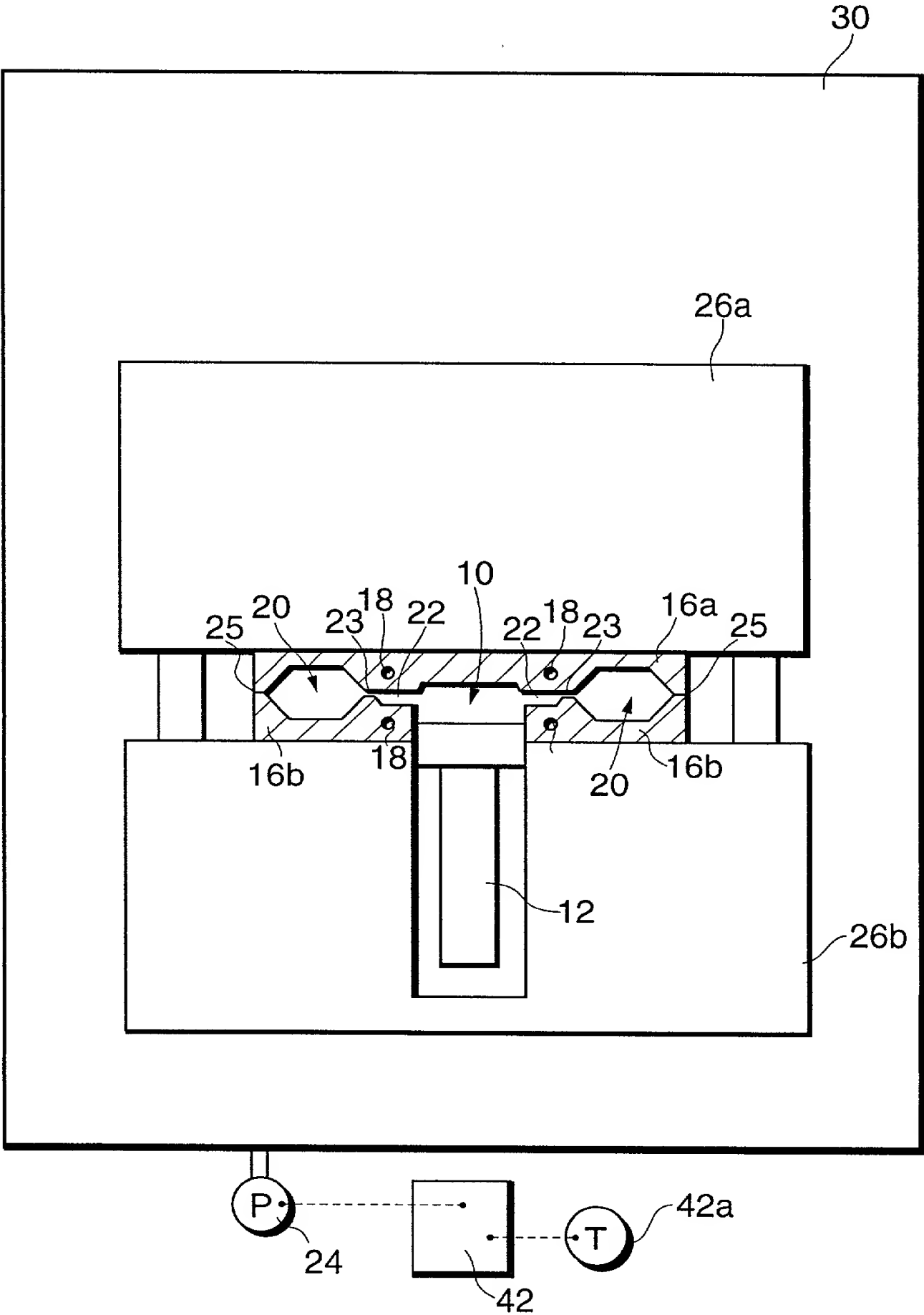
Fig. 1





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Fig.3



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Fig.4(a)

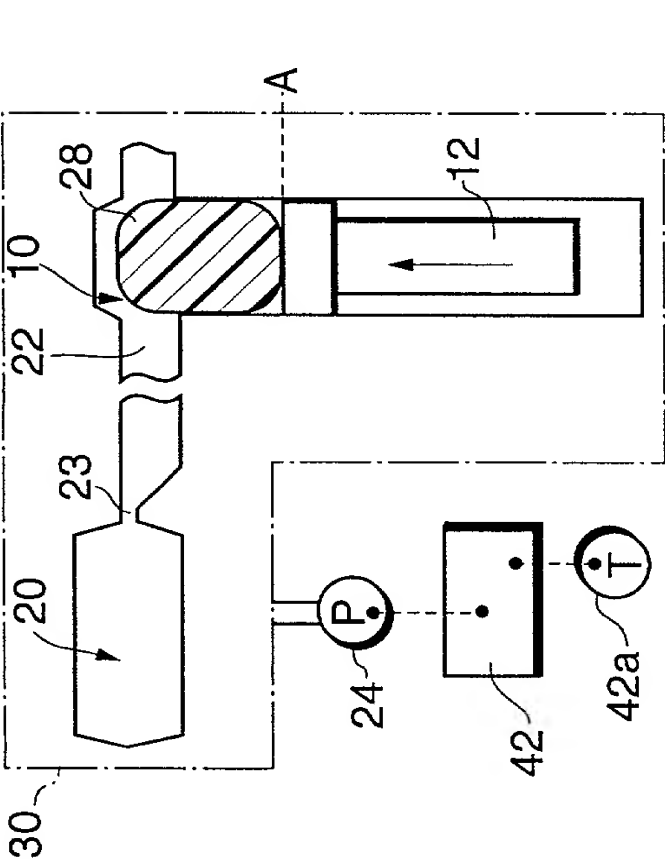


Fig.4(b)

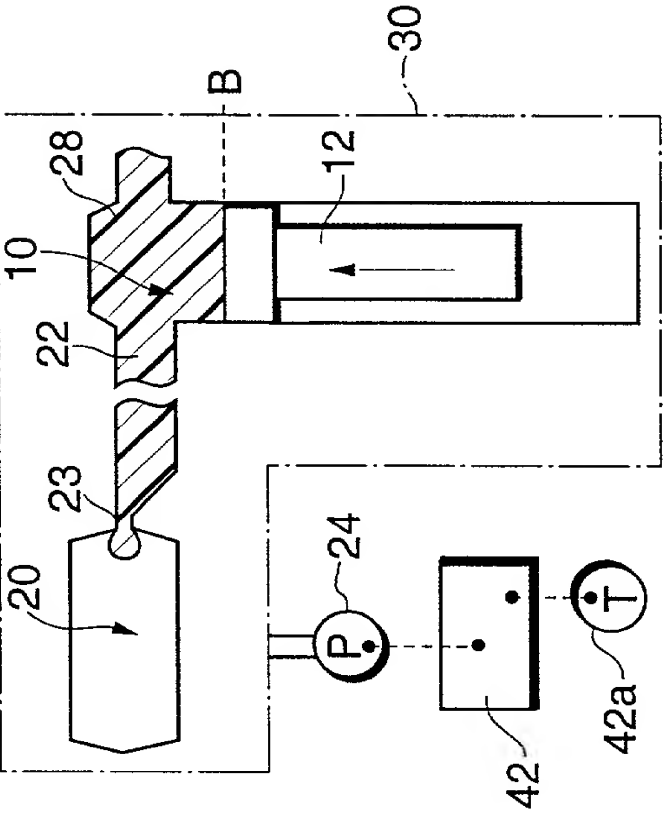


Fig.4(c)

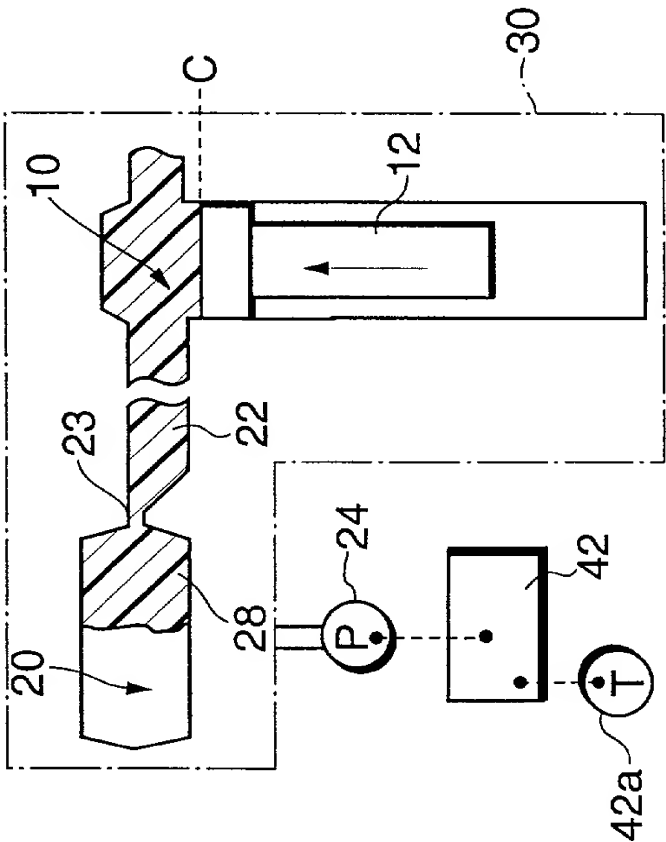
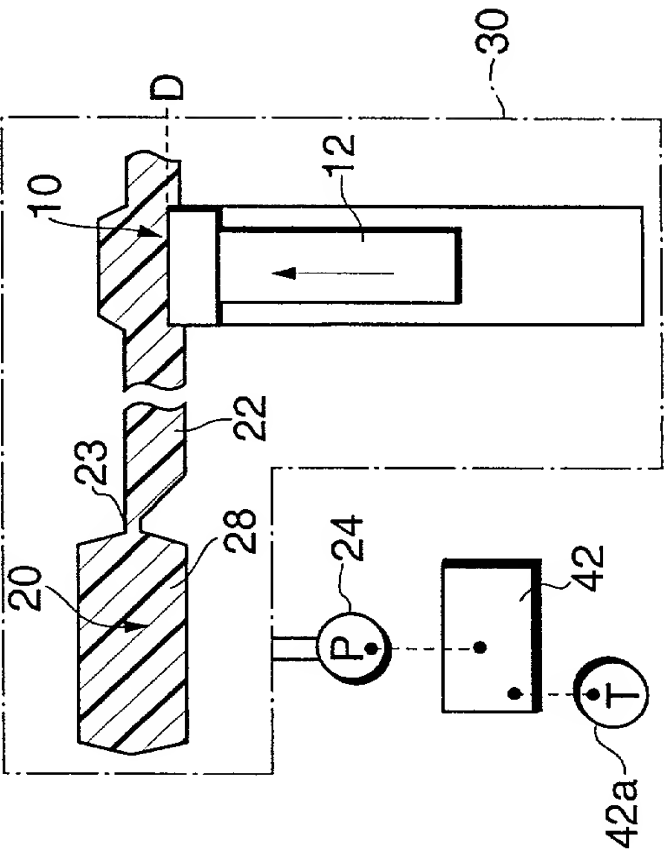
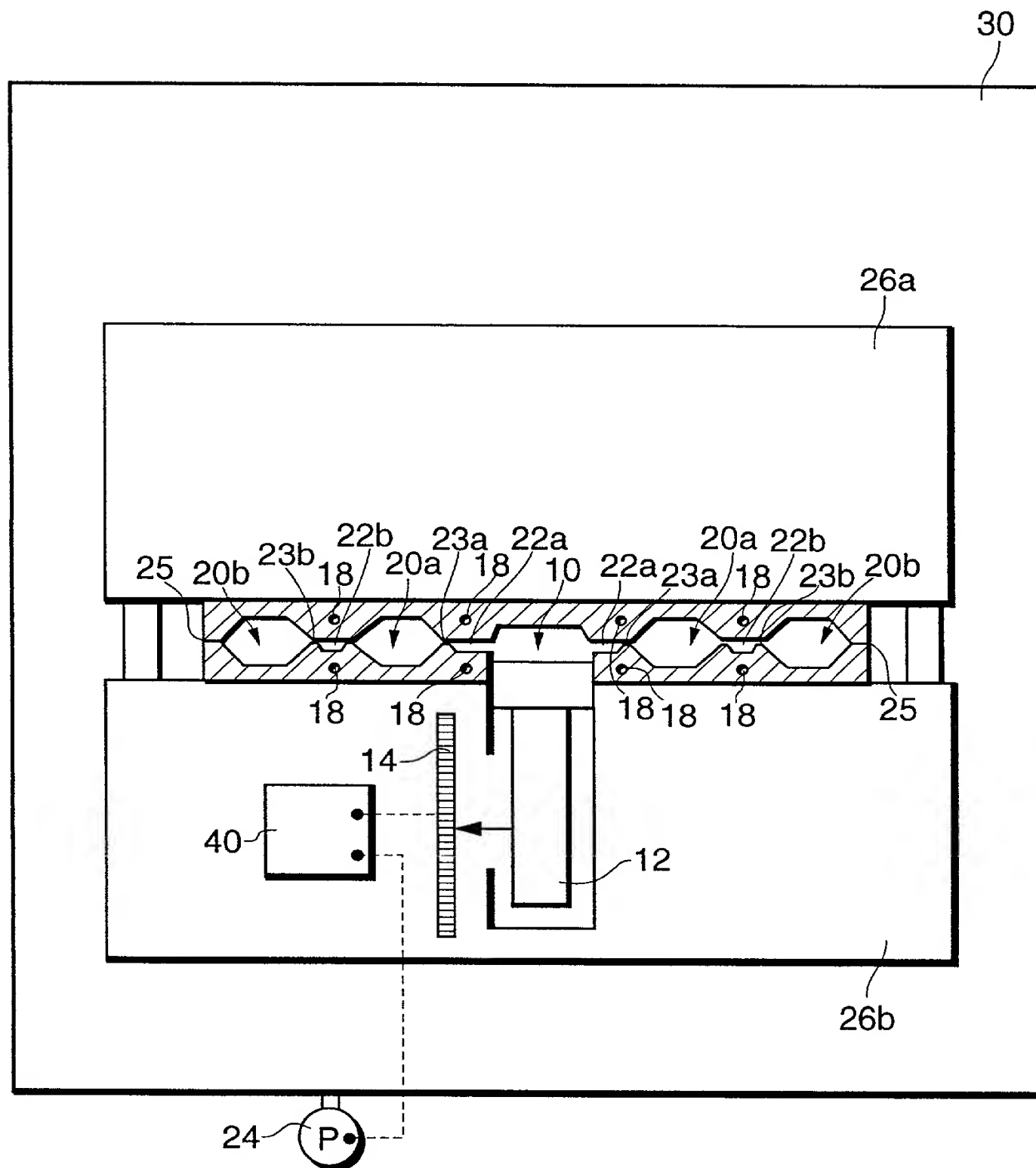


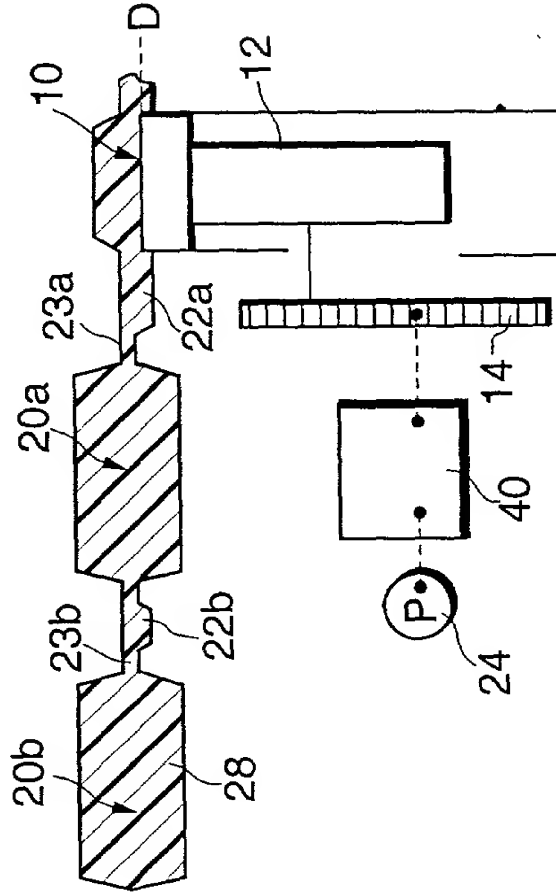
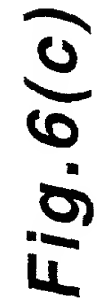
Fig.4(d)



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Fig.5





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Fig. 8(a)

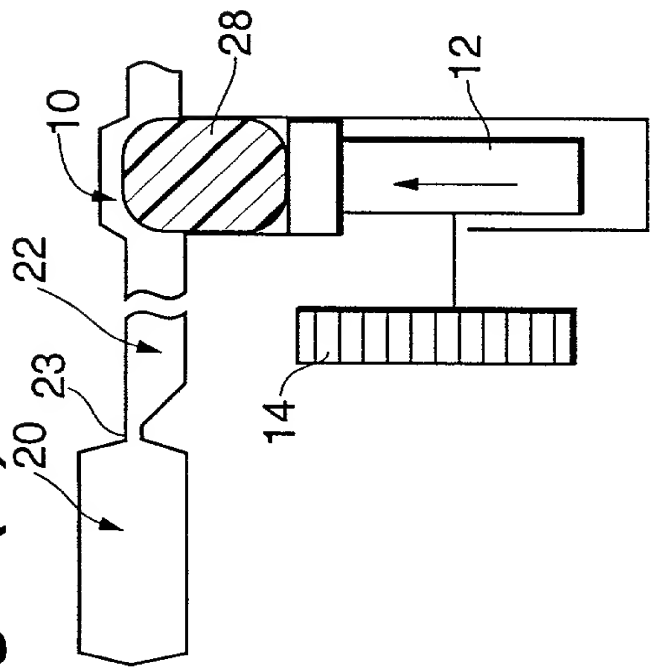


Fig. 8(b)

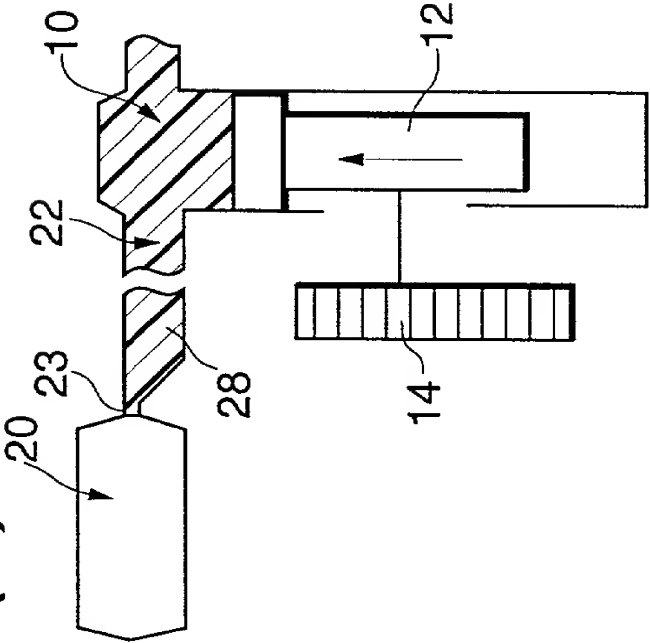


Fig. 8(c)

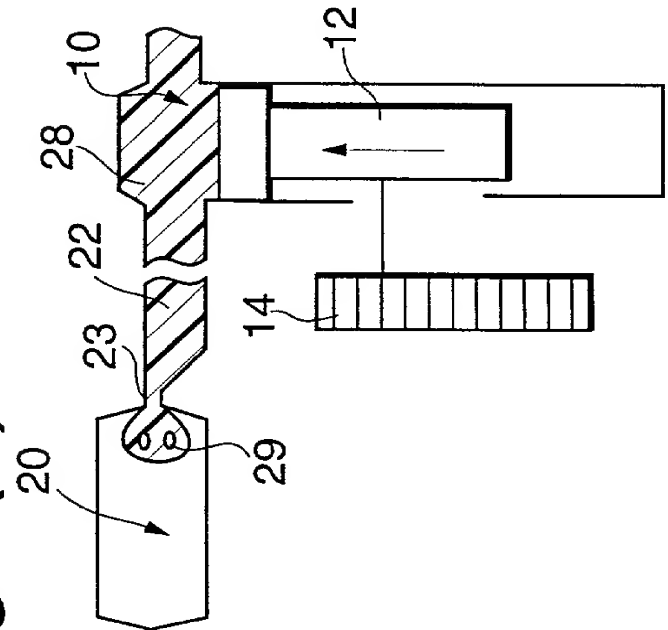


Fig. 8(d)

